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CERMET PLATINUM PALLADIUM SILVER CONDUCTOR 9562

ESL 9562 is a low cost wire bondable PtPdAg. It exhibits excellent solderability and adhesion with good aged bond retention. ESL 9562 can be used as a termination for 850°C fired resistor series.

PASTE DATA

RHEOLOGY:	Thixotropic, screen printable paste
VISCOSITY: (Brookfield RVT, ABZ Spindle, 10 rpm, 25.5°C±0.5°C)	185±15 Pa·s
BONDING MECHANISM:	MICRO-LOK®
SHELF LIFE: (25°C)	6 months

PROCESSING

SCREEN MESH/EMULSION:	325/25 µm
LEVELING TIME: (25°C)	5-10 minutes
DRYING AT 125°C:	10-15 minutes
FIRING RANGE:	850°C-930°C
OPTIMUM:	930°C
TIME AT PEAK:	10-12 minutes
RATE OF ASCENT/DESCENT:	60°C-100°C/minute
SUBSTRATE OF CALIBRATION:	96% alumina
THINNER:	ESL 401

ESL Affiliates
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TYPICAL PROPERTIES

FIRED THICKNESS:		12.5±2.5 µm
COVERAGE:		90-100 cm^2/g
RESISTIVITY:		6 mΩ/square
PRINTING RESOLUTION: (Line/Space)		250 µm x 250 µm
SOLDER WETTABILITY: (RMA flux, 5 sec. dip)	(62 Sn/36 Pb/2 Ag, 220°C ± 5°C)	very good
	(63 Sn/37 Pb, 250°C±5°C)	good
SOLDER LEACH: (No. of 10 sec. dip to double resistance of 0.25 mm wide x 100 mm long conductor, 62 Sn/36 Pb/2 Ag, 220°C±5°C)		6-12
ADHESION: (90° pull, 2.0 mm x 2.0 mm pads, 62 Sn/36 Pb/2 Ag)		
	Initial pull strength:	> 44 N
	Aged 48 hours at 150°C:	26-44 N
ULTRASONIC WIRE BOND: (25 µm Al wire)		8-10 grams
THERMOSONIC WIRE BOND: (25 µm Au wire)		5-8 grams
MIGRATION RESISTANCE:		fair to poor
		Excellent when protected with ESL 4904 or similar overglaze
COMPATIBILITY:	MULTILAYER DIELECTRIC	4905-C
	RESISTORS	ESL 3900 Series
	SOLDER PASTE	ESL 3701